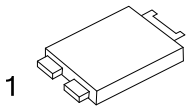
8A SCHOTTKY BARRIER RECTIFIER



TO-277

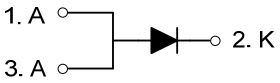
■ DESCRIPTION

The UTC **SB8U60** is a 8A schottky barrier rectifier, it uses UTC's advanced technology to provide the customers with sort, fast switching capability and low forward voltage drop, etc.

■ FEATURES

* Sort, fast switching capability * High efficiency
* Low forward voltage drop

■ SYMBOL



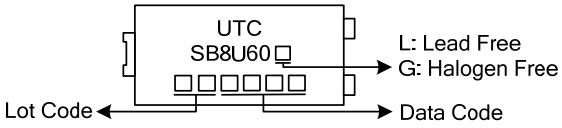
■ ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
SB8U60L-T27-R	SB8U60G-T27-R	TO-277	A	K	A	Tape Reel

Note: Pin Assignment: A: Anode K: Common Cathode

SB8U60L-T27-R (1)Packing Type (2)Package Type (3)Green Package	(1) R: Tape Reel (2) T27: TO-227 (3) L: Lead Free, G: Halogen Free and Lead Free

■ MARKING



■ ABSOLUTE MAXIMUM RATINGS (T_A=25°C unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitance load, derate current by 20%.

PARAMETER	SYMBOL	RATINGS	UNIT
Peak Repetitive Reverse Voltage	V_{RRM}	60	V
Working Peak Reverse Voltage	V_{RWM}	60	V
DC Blocking Voltage	V_{RM}	60	V
Average Rectified Output Current	I_O	8	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	280	A
Operating Junction Temperature	T_J	-65~ +150	°C
Storage Temperature	T_{STG}	-65~ +150	°C

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

■ THERMAL CHARACTERISTICS

PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	θ_{JA}	60	°C/W
Junction to Case (Note)	θ_{JC}	13	°C/W

Note: Polymide PCB, 2 oz. Copper.

■ ELECTRICAL CHARACTERISTICS (T_A=25°C unless otherwise specified.)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Forward Voltage Drop	V_F	I_F=1.0A, T_J=25°C		0.30	0.35	V
		I_F=8A, T_J=25°C		0.46	0.53	V
		I_F=8A, T_J=125°C			0.5	V
Reverse Current (Note 2)	I_R	V_R = 60V, T_J=25°C		0.12	0.6	mA
		V_R = 60V, T_J=125°C			100	mA

Notes: 1. Theoretical θ_{JS} calculated from the top center of the die straight down to the PCB cathode tab solder junction.
2. Short duration pulse test used to minimize self-heating effect.